

Title (en)
CURRENT-CARRYING CONNECTING ELEMENTS FOR PLATE CONDUCTORS CONSISTING OF HIGH-TEMPERATURE SUPRACONDUCTIVE THIN LAYERS

Title (de)
STROMTRAGENDE VERBINDUNGSELEMENTE FÜR PLATTENLEITER AUS HOCHTEMPERATUR-SUPRALEITENDEN DÜNNSCHICHTEN

Title (fr)
ELEMENTS DE LIAISON PORTEURS DE COURANT ET DESTINES A DES PLAQUES CONDUCTRICES REALISEES EN MINCES COUCHES SUPRACONDUCTRICES HAUTE TEMPERATURE

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Abstract (en)
[origin: DE19928324A1] The invention relates to current-carrying connecting elements for plate conductors consisting of high-temperature supraconductive thin layers, especially for resistive current-limiting devices in switchgear assemblies used for supplying and distributing energy. At least two plate conductors that are situated one behind the other are electroconductively connected by the current-carrying connecting elements and are provided with electrical contact surfaces for receiving current supply lines. The current-carrying connecting elements consist of high-temperature supraconductive strips (HTSL-BD) which are electroconductively connected to the high temperature supraconductive thin layers (HTSL-DS) by material and/or nonpositive fit conducting connections (LV). The approximately arch-shaped cross-sectional contour of the high temperature supraconductive strips (HTSL-BD) is adapted to the distance between the high-temperature supraconductive thin layers (HTSL-DS) to be connected. The current-carrying connecting elements and the plate conductors are constituent parts of resistive current-limiting devices in switchgear assemblies used for supplying and distributing energy.

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